

Datasheet revision 1.0

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## Solder Wire Sn96.5/Ag3.5 No-Clean with 2.0% Flux Core 0.3oz Tube

Product Highlights No-Clean Synthetic Flux Core The clear, non-corrosive, non-conductive residue is meant to be left on the board. 2.0% flux core Halogen content: None RoHS II and REACH compliant

## **Specifications**

Alloy: Wire Diameter: Flux Type: Flux Classification: Melting Point: Packaging: Sn96.5/Ag3.5 0.020" (0.5mm) No-Clean Synthetic ROL0 221°C (430°F) 0.3oz Tube



## **Test Results**

Test J-STD-004 or other	Test Requirement	Result
requirements as stated		
Copper Mirror	IPC-TM-650: 2.3.32	L: No breakthrough
Corrosion	IPC-TM-650: 2.6.15	L: No corrosion
Quantitative Halides	IPC-TM-650: 2.3.28.1	L: <0.5%
Electrochemical Migration	IPC-TM-650: 2.6.14.1	L: <1 decade drop (No-clean)
Surface Insulation Resistance 85°C,	IPC-TM-650: 2.6.3.7	L: ≥100MΩ (No-clean)
85% RH @ 168 Hours		
Visual	IPC-TM-650: 3.4.2.5	Clear and free from precipitation
Conflict Minerals Compliance	Electronic Industry Citizenship	Compliant
	Coalition (EICC)	
REACH Compliance	Articles 33 and 67 of Regulation (EC)	Contains no substance >0.1% w/w that
	No 1907/2006	is listed as a SVHC or restricted for
		use in solder materials

Conforms to the following Industry Standards:J-STD-004B, Amendment 1 (Solder Fluxes):YesJ-STD-006C, Amendments 1 & 2 (Solder Alloys and Fluxed/Non-Fluxed Solders):YesRoHS 2 Directive 2011/65/EU:Yes